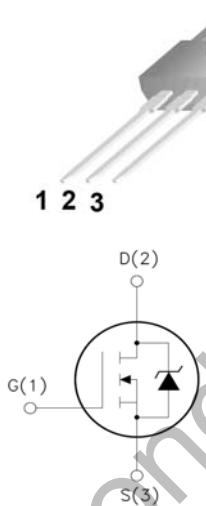


 WGF85N06 60V N-Channel MOSFET	 TO-220F   <p> 1. Gate (G) 2. Drain (D) 3. Source (S) </p>
------------------------------------------------------------------------------------------------------------------------------	-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------

Absolute Maximum Ratings* (T_c=25°C Unless otherwise noted)

Symbol	PARAMETER	Value	Unit
V _{DSS}	Drain-Source Voltage	60	V
I _D	Drain Current	T _c =25°C	85
		T _c =100°C	65
V _{GS(TH)}	Gate Threshold Voltage	±25	V
E _{AS}	Single Pulse Avalanche Energy (note1)	100	mJ
I _{AR}	Avalanche Current (note2)	85	A
P _D	Power Dissipation (T _c =25°C)	65	W
T _j	Junction Temperature(MAX)	150	°C
T _{stg}	Storage Temperature	-55~+150	°C
T _L	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	PARAMETER	Typ.	MAX.	Unit
R _{θJC}	Thermal Resistance,Junction to Case	-	1.92	°C/W
R _{θJA}	Thermal Resistance,Junction to Ambient	-	62.5	°C/W

Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	-	-	V
Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	I_{DSS}	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	I_{DSS}	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$	-	-	10	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	-	4	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$	-	6.7	7.0	$\text{m}\Omega$
Dynamic Characteristics						
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=40\text{A}$	-	105	-	S
Input Capacitance	C_{iss}	$V_{\text{DS}}=35\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	3091	-	PF
Output Capacitance	C_{oss}		-	292	-	PF
Reverse Transfer Capacitance	C_{rss}		-	219	-	PF
Total Gate Charge	Q_g		-	72	-	nC
Gate-Source Charge	Q_{gs}	$V_{\text{DS}}=32\text{V}, I_{\text{D}}=40\text{A}, V_{\text{GS}}=10\text{V}$	-	17	-	nC
Gate-Drain Charge	Q_{gd}		-	26	-	nC
Switching times						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=32\text{V}, I_{\text{D}}=40\text{A}, R_{\text{L}}=15\Omega, V_{\text{GS}}=10\text{V}, R_{\text{G}}=2.7\Omega$	-	13	-	nS
Turn-on Rise Time	t_r		-	75	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	46	-	nS
Turn-Off Fall Time	t_f		-	73	-	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I_{SD}		-	-	85	A
Pulsed Source-drain current(Body Diode)	I_{SDM}		-	-	300	A
Forward on voltage ^(Note 1)	V_{SD}	$T_j=25^\circ\text{C}, I_{\text{SD}}=85\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.5	V
Reverse Recovery Time ^(Note 1)	t_{rr}	$T_j=25^\circ\text{C}, I_F=85\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	36	-	nS
Reverse Recovery Charge ^(Note 1)	Q_{rr}		-	43	-	nC
Forward Turn-on Time	t_{on}	Intrinsic turn-on time is negligible(turn-on is dominated by L_s+L_d)				

Notes 1.Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1.5\%$, $R_G=25\Omega$, Starting $T_j=25^\circ\text{C}$

Typical Electrical and Thermal Characteristics (curves)

Fig 1: Output Characteristics

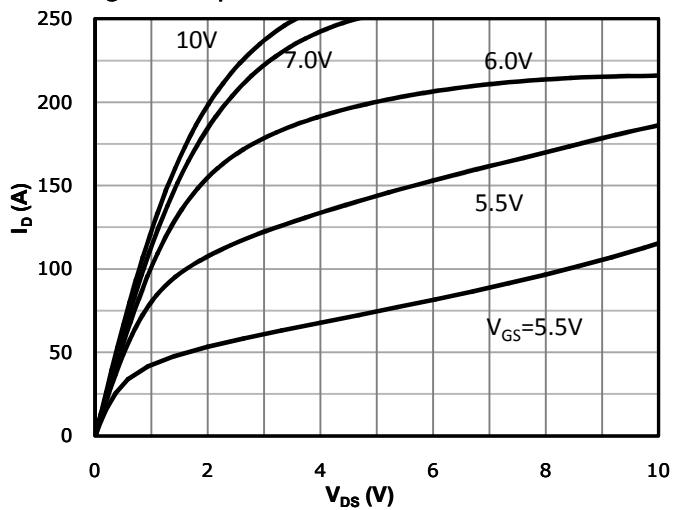


Fig 2: Transfer Characteristics

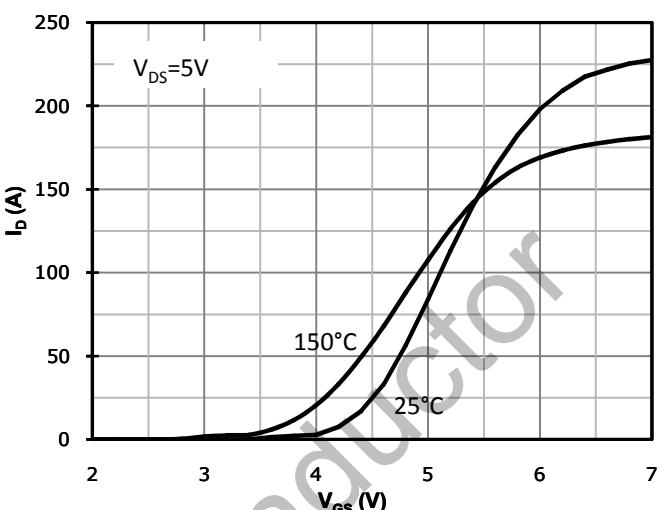


Fig 3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

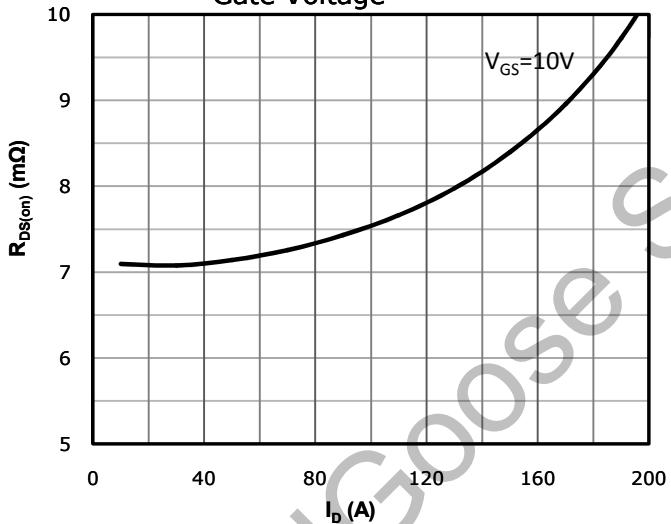


Fig 4: $R_{DS(on)}$ vs Gate Voltage

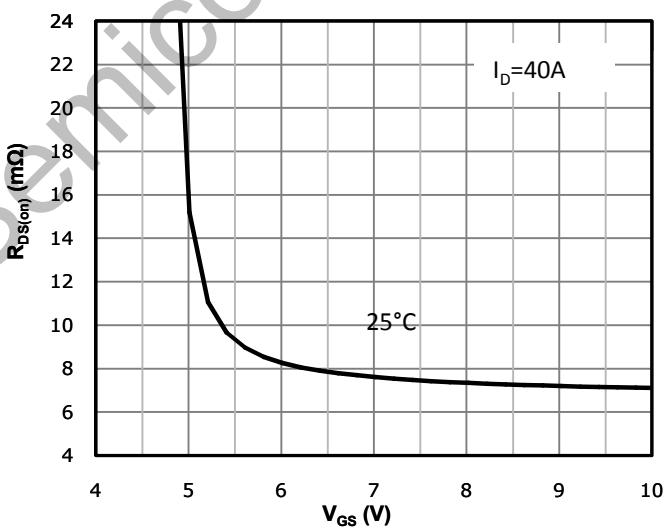


Fig 5: $R_{DS(on)}$ vs. Temperature

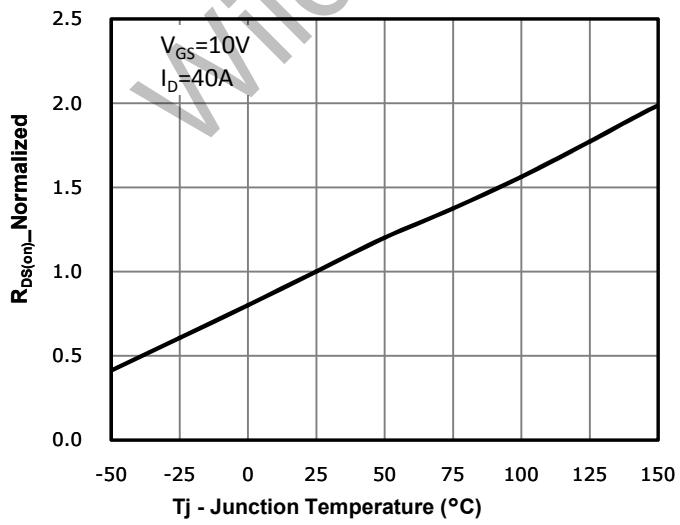


Fig 6: Capacitance Characteristics

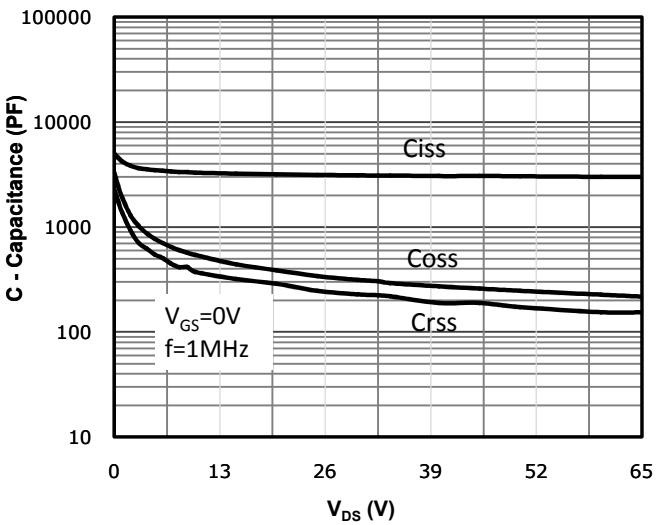


Fig 7: Gate Charge Characteristics

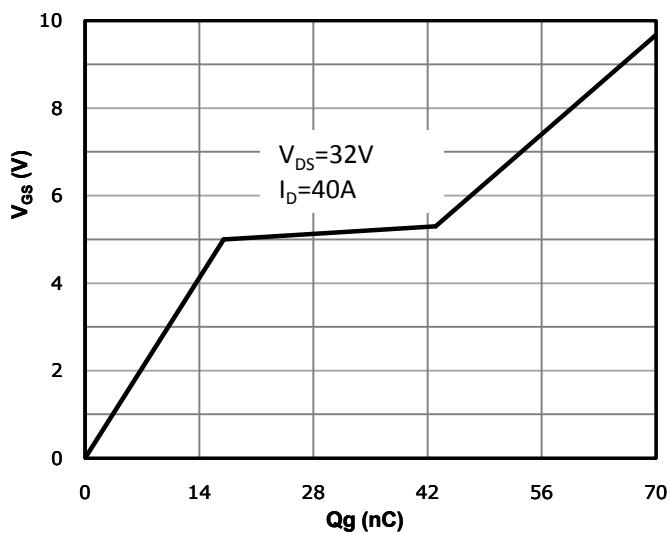


Fig 8: Body-diode Forward Characteristics

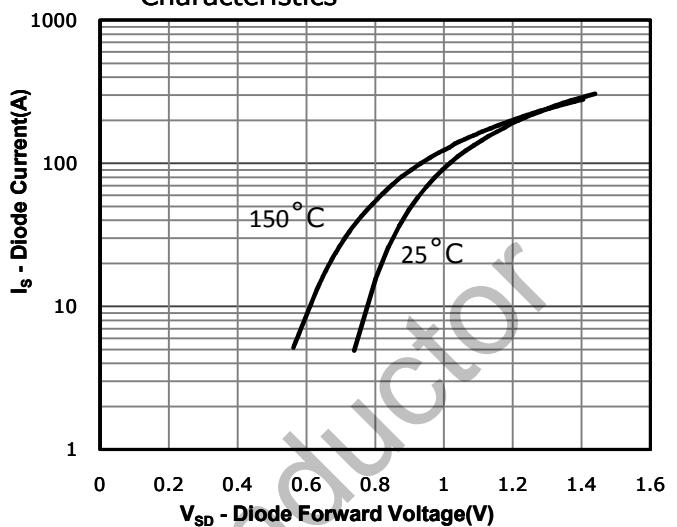


Fig 9: Power Dissipation

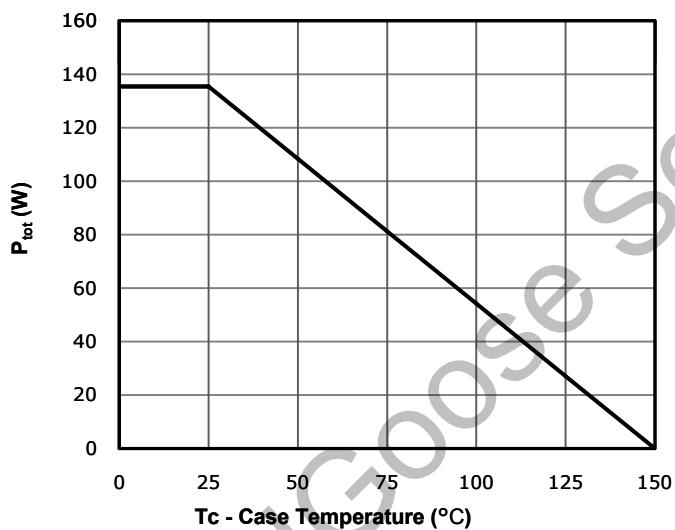


Fig 10: Drain Current Derating

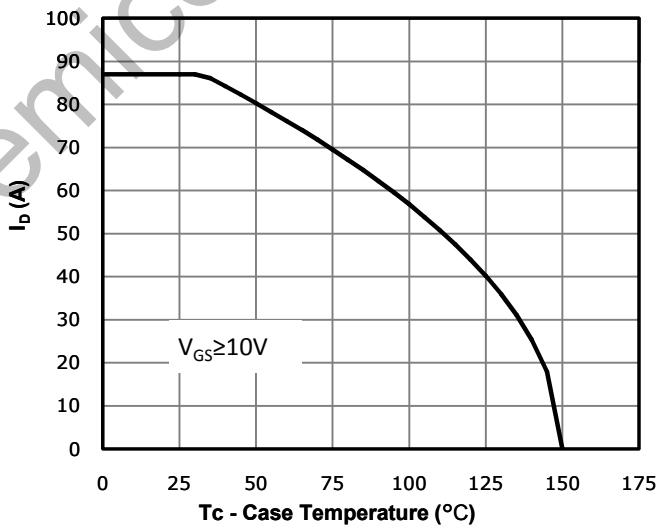


Fig 11: Safe Operating Area

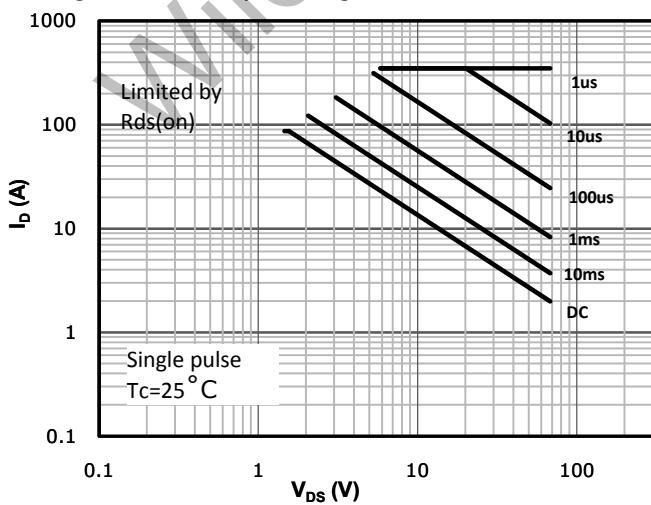
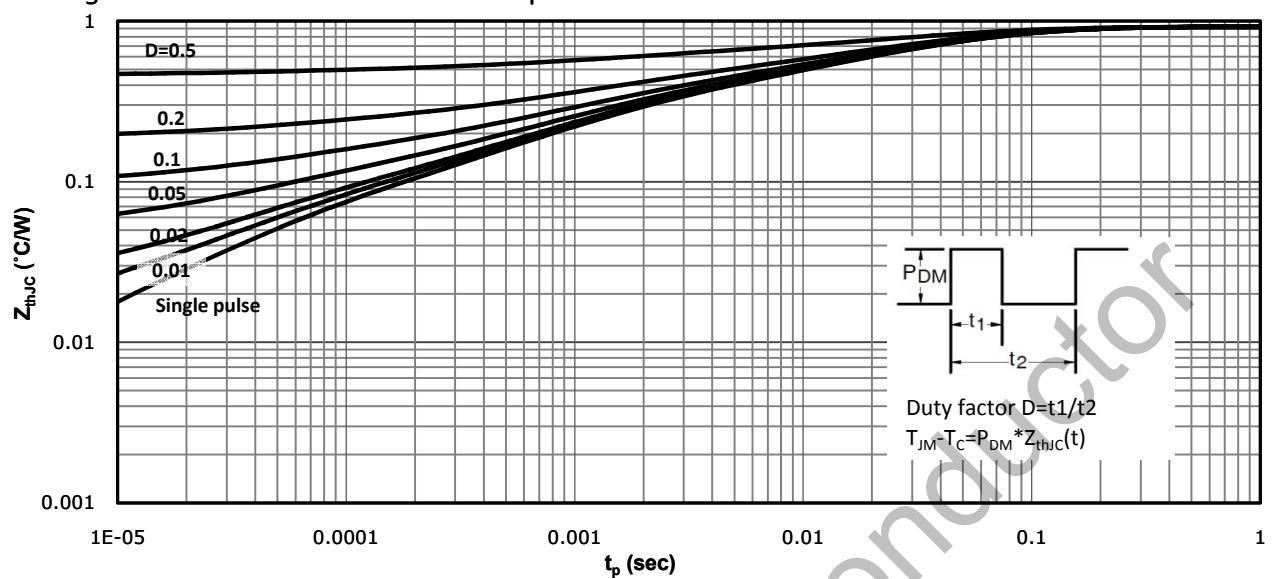
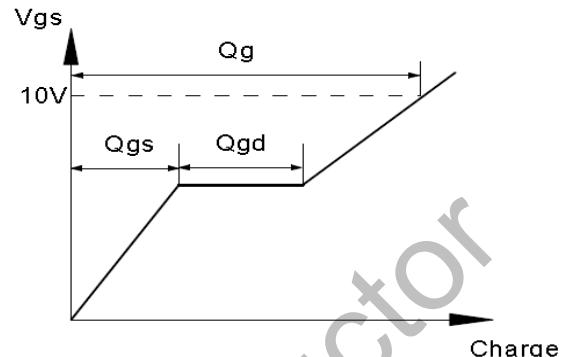
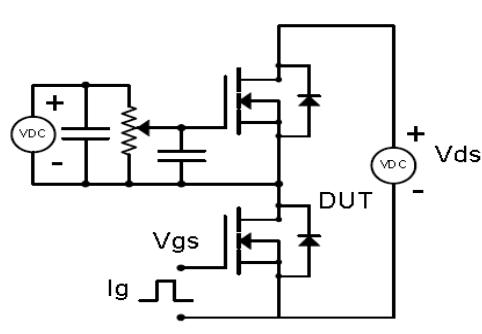


Fig 12: Max. Transient Thermal Impedance

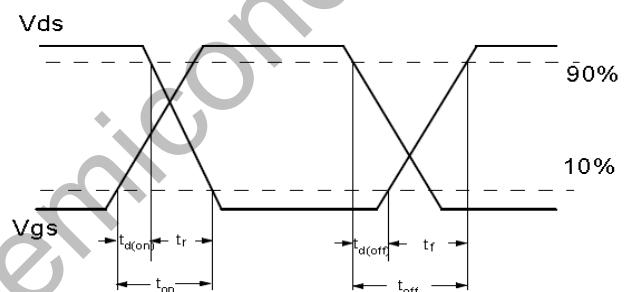
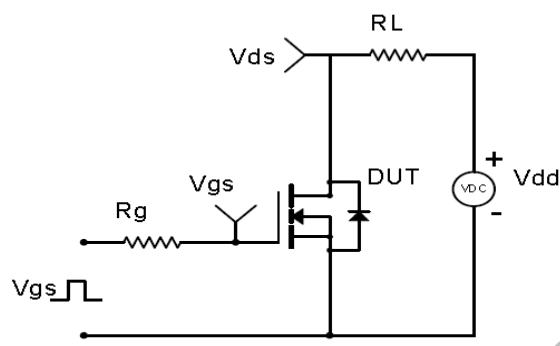


Test Circuit & Waveform

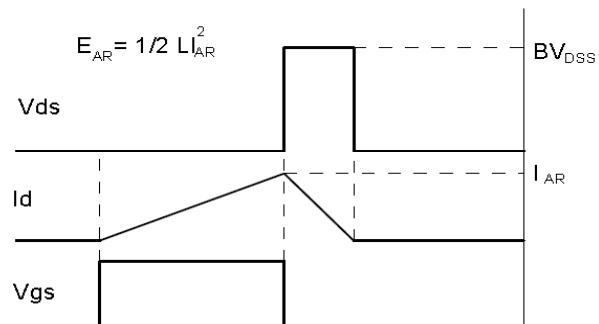
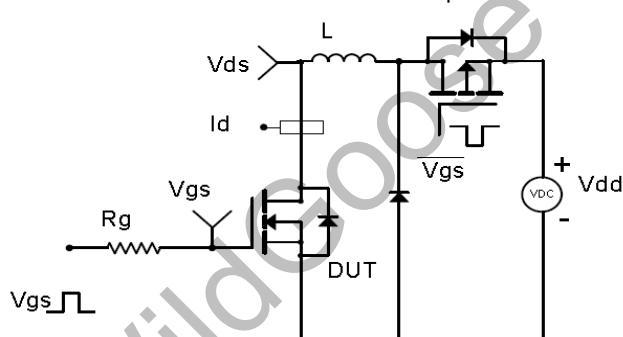
Gate Charge Test Circuit & Waveform



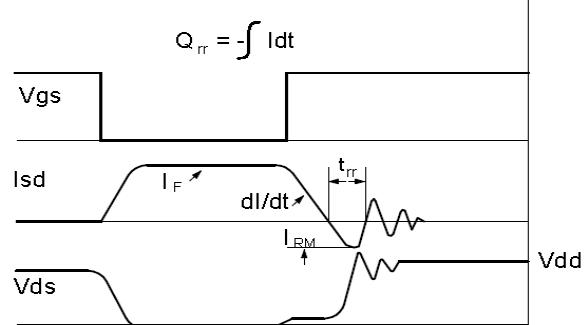
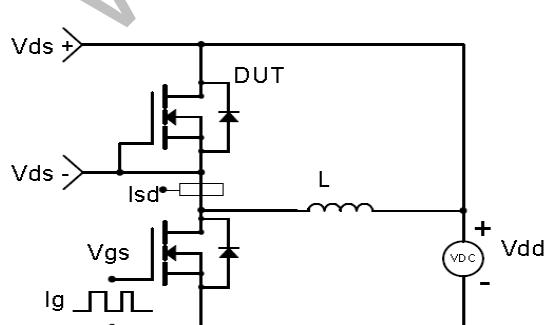
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



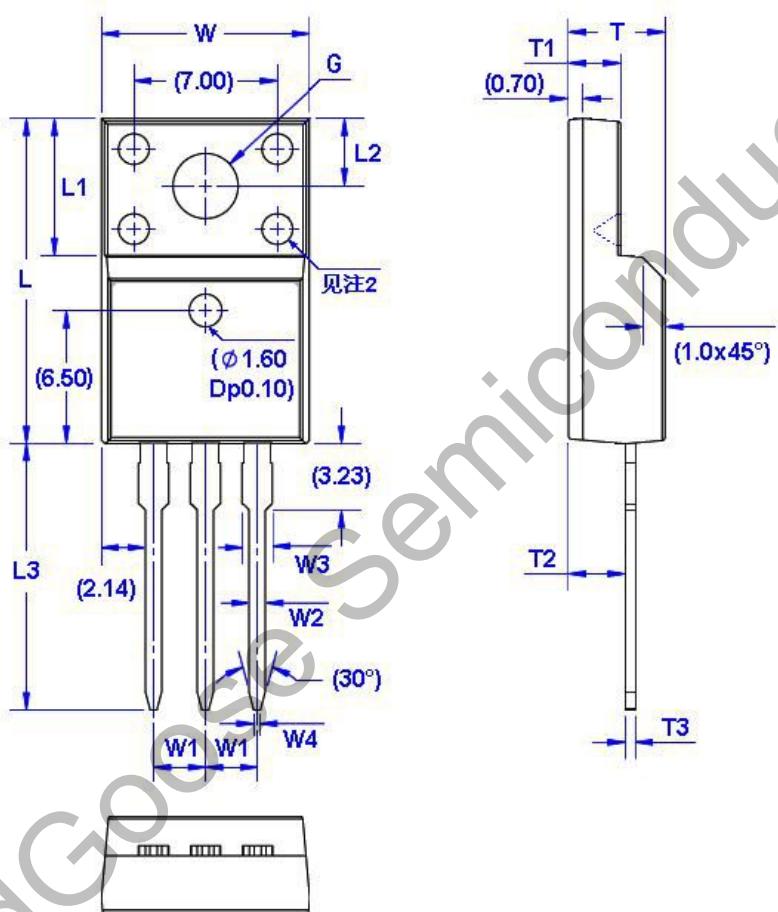
Diode Recovery Test Circuit & Waveforms



Package Dimension

TO-220F

Unit: mm



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.96	10.36	W4	0.25	0.45	L3	12.78	13.18	T3	0.45	0.60
W1	2.54 (TYP)		L	15.67	16.07	T	4.50	4.90	G(Φ)	3.08	3.28
W2	0.70	0.90	L1	6.48	6.88	T1	2.34	2.74			
W3	1.24	1.47	L2	3.20	3.40	T2	2.56	2.96			